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**DECLARATION - USA PATENT APPLICATION**

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name;

I believe I am an original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled POLISHING PAD AND METHOD OF PRODUCING SEMICONDUCTOR DEVICE; PCT Application No. PCT/JP2003/015128 filed in the Japanese Receiving Office on November 27, 2003; the documentation for entry into the U.S. national phase of which was filed on May 26, 2005 as Application Serial No. 10/536,621;

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above;

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56;

I hereby claim foreign priority benefits under Title 35, United States Code, § 119(a)-(d) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

PRIOR FOREIGN APPLICATION(S)

Priority  
Claimed

No.: 2002-343199	Country: Japan	Date Filed: November 27, 2002	Yes
No.: 2003-000331	Country: Japan	Date Filed: January 6, 2003	Yes
No.: 2003-029477	Country: Japan	Date Filed: February 6, 2003	Yes
No.: 2003-064653	Country: Japan	Date Filed: March 11, 2003	Yes

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful, false statements may jeopardize the validity of the application or any patent issued thereon.

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Full name of first inventor: **Masahiko NAKAMORI**

Inventor's signature \_\_\_\_\_

Date \_\_\_\_\_

Residence: c/o Toyo Boseki Kabushiki Kaisha Research Center, 1-1, Katata, 2-chome, Ohtsu-shi,  
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Full name of second inventor: **Tetsuo SHIMOMURA**

Inventor's signature \_\_\_\_\_

Date \_\_\_\_\_

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Full name of third inventor: **Takatoshi YAMADA**

Inventor's signature \_\_\_\_\_

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Full name of fourth inventor: **Kazuyuki OGAWA**

Inventor's signature \_\_\_\_\_

Date \_\_\_\_\_

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Full name of fifth inventor: **Atsushi KAZUNO**

Inventor's signature \_\_\_\_\_

Date \_\_\_\_\_

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Full name of sixth inventor: **Masahiro WATANABE**

Inventor's signature *Masahiro Watanabe*

Date February 27, 2008

Residence: Residence: **c/o Toyo Tire & Rubber Co., Ltd., 17-18, Edobori 1-chome, Nishi-ku,  
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